

MSKSEMI

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT



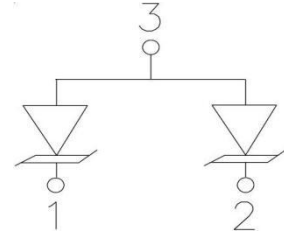
PLED

Product data sheet

Features

- ◆ 150 Watts peak pulse power ($t_p = 8/20\mu s$)
- ◆ Transient protection for high speed data lines to IEC 61000-4-2 (ESD) $\pm 15kV$ (air), $\pm 8kV$ (contact)
IEC 61000-4-4 (EFT) 40A (5/50ns)
- ◆ Working voltages : 5V
- ◆ Protects Two Power or I/O Port
- ◆ Low operating and clamping voltages
- ◆ Solid-state silicon avalanche technology

SOT-523



Applications

- ◆ Notebooks, Desktops, Servers and Video Graphics Cards
- ◆ USB Power & Data Line Protection
- ◆ Monitors and Flat Panel Displays
- ◆ I²C Bus Protection
- ◆ Portable Instrumentation
- ◆ Set Top Box

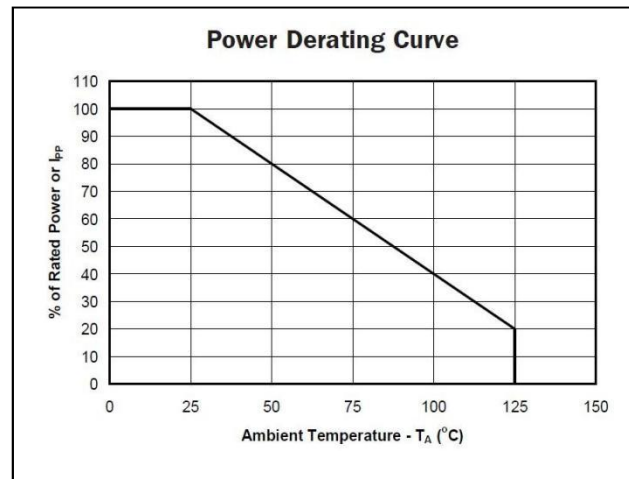
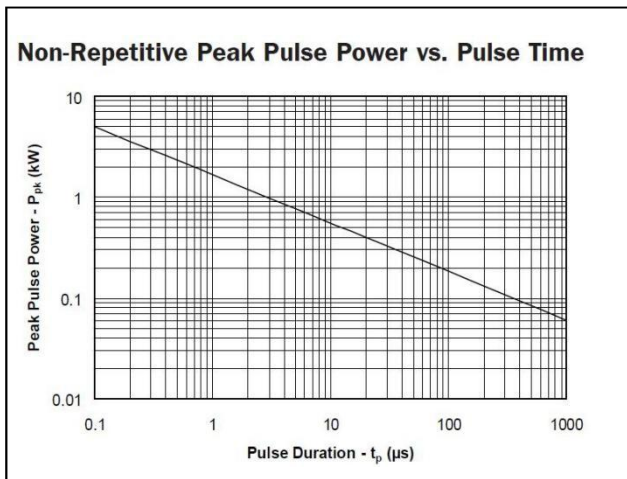
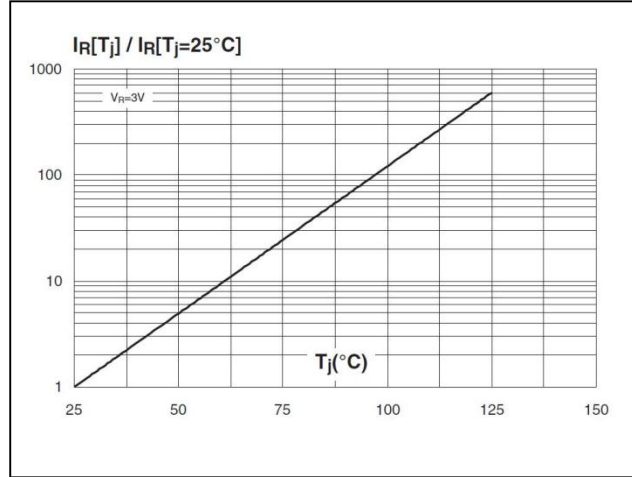
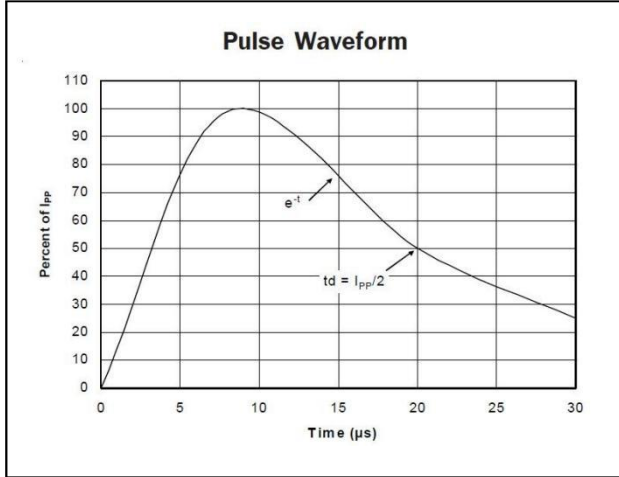
Electrical Characteristics @ Ta=25°C unless otherwise

P/N	VRWM @IR		VBR@ImA	VC@1	VC@IPP		CJ
	V	μA	V	V	V	A	pF
		MAX	MIN	MAX	MAX		MAX
RCLAMP0502BATCT	5	1	6	9.8	15	3	0.9

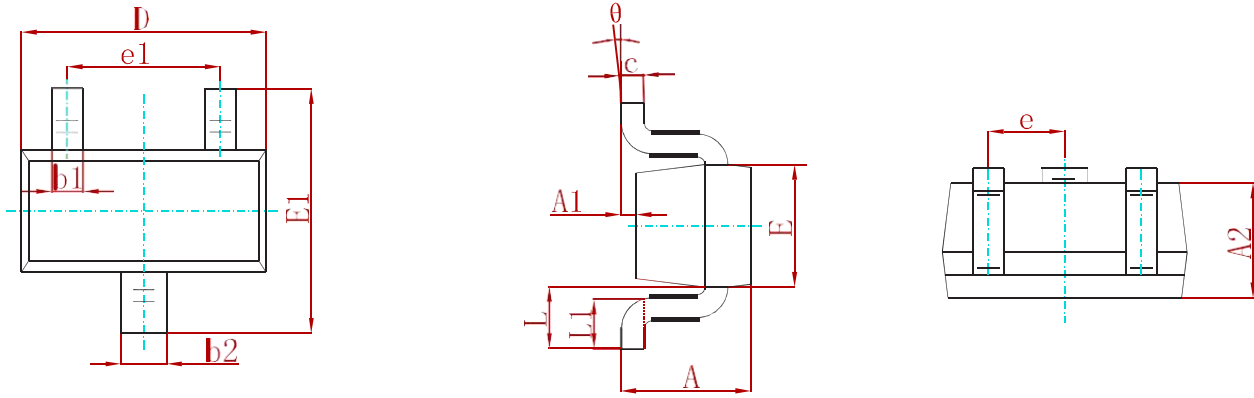
Maximum Rating @ Ta=25°C unless otherwise specified

Symbol	Parameter	Ratings	Units
P _{PK}	Peak Pulse Power ($t_p = 8/20\mu s$)	150	Watts
T _L	Lead Soldering Temperature	260(10sec.)	°C
T _J	Operating Temperature	-55 to +125	°C
T _{STG}	Storage Temperature	-55 to +150	°C

Typical Characteristics @ $T_a=25^\circ\text{C}$ unless otherwise specified

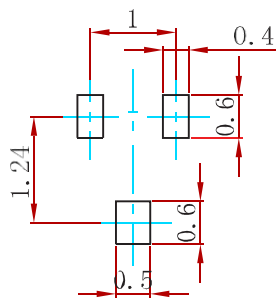


PACKAGE MECHANICAL DATA



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.700	0.900	0.028	0.035
A1	0.000	0.100	0.000	0.004
A2	0.700	0.800	0.028	0.031
b1	0.150	0.250	0.006	0.010
b2	0.250	0.350	0.010	0.014
c	0.100	0.200	0.004	0.008
D	1.500	1.700	0.059	0.067
E	0.700	0.900	0.028	0.035
E1	1.450	1.750	0.057	0.069
e	0.500 TYP.		0.020 TYP.	
e1	0.900	1.100	0.035	0.043
L	0.400 REF.		0.016 REF.	
L1	0.260	0.460	0.010	0.018
theta	0°	8°	0°	8°

Suggested Pad Layout



- Note:
1. Controlling dimension: in millimeters.
 2. General tolerance: ±0.05mm.
 3. The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
RCLAMP0502BATCT	SOT-523	3000

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